



創新

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卓越

Best



科技

Technology

# Investor Conference

Stock Symbol: 1595

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Ray Lu, the President of BHT  
November 9<sup>th</sup>, 2022

# Disclaimer

This presentation, which included statements regarding its results of operations, financial conditions, and business prospects, are only based on the Company's estimates and expectations and are for reference only. Any business outlook or forward-looking statement hereof is subject to change after this date. Except as required by law, we undertake no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.



# Outline

Operation Overview

Financial Overview

Future Outlook

Conglomerate Layout

Q&A





# Group Members and Key Affiliated Enterprises

*Chime Ball Technology Co., Ltd.*

Flexible/Rigid PCB Exposure Units

Flexible PCB RTR Exposure Units

Flexible/Rigid PCB LDI/Solder Mask DI Exposure Units

Research and Development

Wafer Manufacturing Units

Handling Systems in Wafer Fab

Key Parts Supplier

*Bao Hong Semi Tech Co., Ltd.*

International Trading Company for

Parts Sales

Maintenance

After-Sales Service

SEMI 2D/3D AOI

Automated Software Development

*CBT International (SH) Co., Ltd.*

*Bao Hua Technology Co., Ltd.*

PEALD/ALE Thin Film/Etch Process Application

PEALD/ALE Thin Film/Etch Process Patent  
Portfolio

*Pure Metallica Co., Ltd.*

# Group Members' Locations

In order to meet the needs of the PCB/semiconductor industry, CBT group has established 5 service points with high-quality service and sales network around the world.

- ✓ *Taiwan*
- ✓ *China*
- ✓ *South Korea*
- ✓ *Thailand*
- ✓ *USA*



# Diversified Product Line

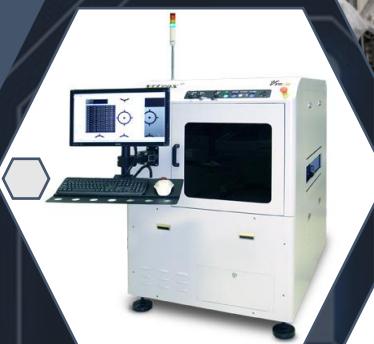


8" & 12"  
SEMI Legacy  
Process Tool

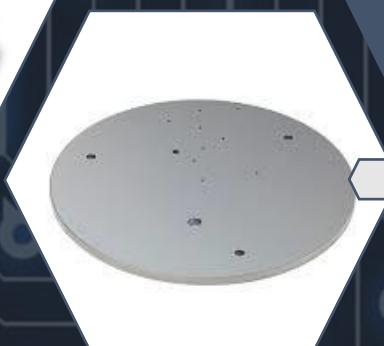


Back-End  
Package and  
PCB Exposure  
Units

2D/3D AOI



PEALE/ALD



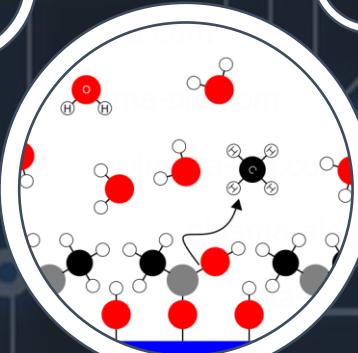
Spare Parts  
Sales Agent



Advanced  
Surface  
Treatment  
(AST)

# Patent Portfolio

Exposure Units & Direct Imaging Systems  
63 Patents



PECVD (ALD) & ALE  
25 Patents



Semi Fab Tools Automation, N2  
EFEM (ATM), VTM Transfer Module  
10 Patents

Business Units of CBT Group continue to dedicate to researching and developing new equipment, and are applying for various patents to protect our achievements and maintain competitiveness in the industries.



# Operating Performance and Financial Statements

# 2018~2022 Q3 Consolidated Revenue, Gross Margin, Net Profit Margin, EPS and Dividend Yield

Unit: NT\$ thousand

Account	2018	2019	2020	2021	2022 Q3
Consolidated Revenue	1,756,286	1,729,528	1,692,149	2,417,036	1,418,639
Gross Margin	30.31%	25.91%	21.83%	25.09%	25.13%
Net Profit Margin	11.19%	5.58%	0.51%	7.63%	16.32%
EPS	4.18	2.06	0.18	3.93	4.98
Dividend Yield	4.08%	2.97%	1.46%	4.74%	-
BVPS	51.6	50.78	49.69	53.4	56.81

# Consolidated Income Statement for 2021 Q3 and 2022 Q3

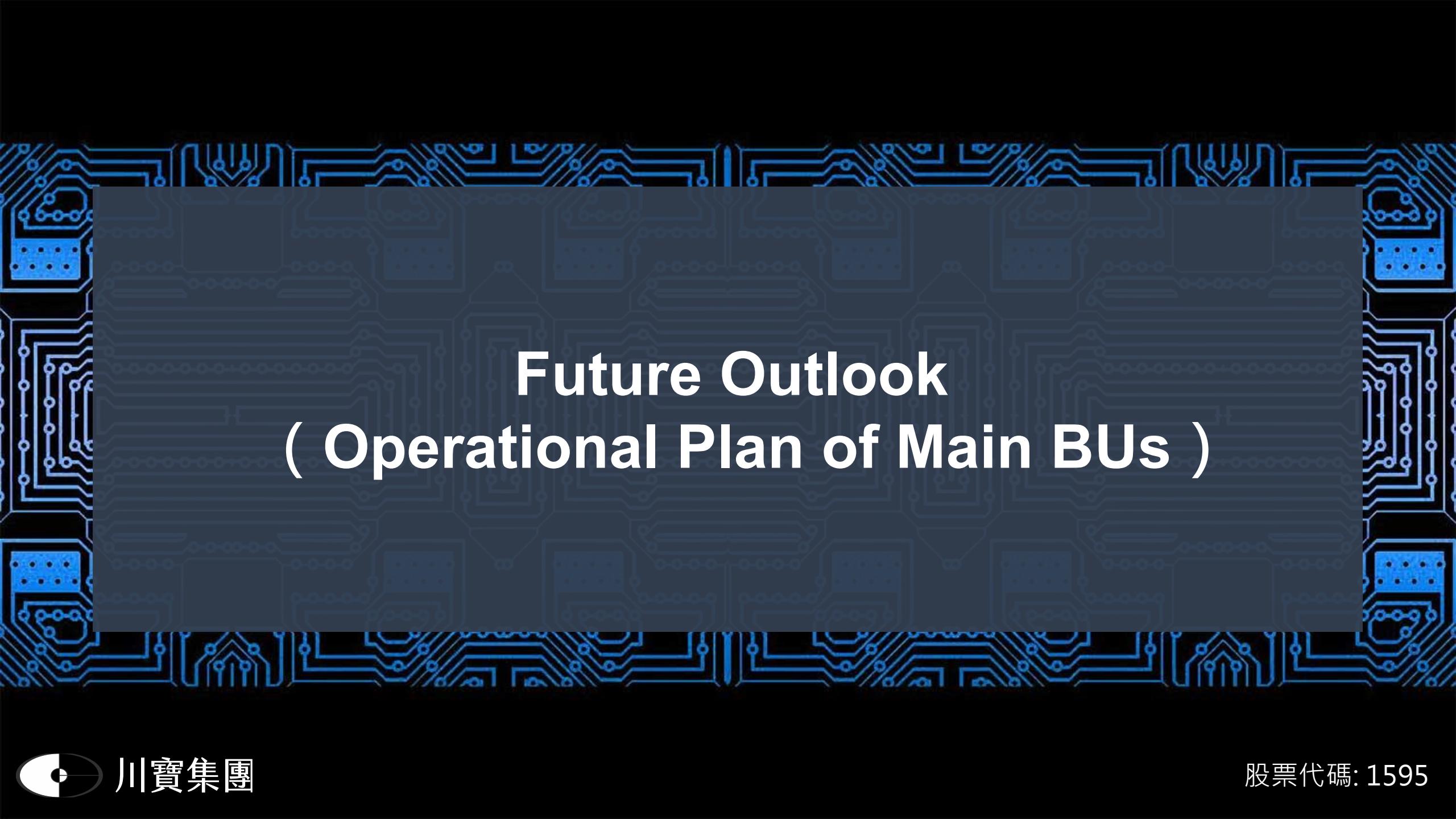
Account	2022 Q3	%	2021 Q3	%	YoY
Operating Revenue	1,418,639	100%	1,750,739	100%	-19%
Gross Profit	356,446	25%	436,824	25%	-18%
Operating Expense	278,527	20%	253,590	14%	10%
Net Operating Profit	77,919	5%	183,234	10%	-57%
Non-Operating Income and Expenditure	231,230	16%	(20,210)	-1%	-1244%
Net Profit before Tax	309,149	22%	163,024	9%	90%
Income Tax Expense	77,625	5%	36,024	2%	115%
Profit after Tax	231,524	16%	127,000	7%	82%
EPS	4.98		2.72		83%

Unit: NT\$ thousand

# Consolidated Balance Sheet 2021 Q3、2021 Q4 and 2022 Q3

Account	2021 Q3	%	2021 Q4	%	2022Q3	%
<b>Cash and Cash Equivalents</b>	931,092	20%	1,019,832	22%	1,415,595	28%
<b>Receivable</b>	932,442	21%	932,822	21%	639,810	12%
<b>Inventory</b>	1,116,996	25%	1,118,223	25%	1,496,776	29%
<b>Other Current Assets</b>	347,579	8%	302,379	7%	419,482	8%
<b>Property, Plant and Equipment</b>	686,611	15%	644,660	14%	748,907	14%
<b>Intangible Assets</b>	388,864	9%	379,860	8%	353,441	7%
<b>Other Non-Current Assets</b>	104,566	2%	107,395	2%	100,155	2%
<b>Total Assets</b>	4,508,150	100%	4,505,171	99%	5,174,166	100%
<b>Current Liabilities</b>	1,902,523	43%	1,775,274	40%	2,254,276	43%
<b>Non-Current Liabilities</b>	146,701	3%	208,488	5%	249,541	5%
<b>Total Liabilities</b>	2,049,224	46%	1,983,762	45%	2,503,817	48%
<b>Common Stock</b>	471,481	10%	471,481	10%	469,261	9%
<b>Additional Paid-In Capital</b>	552,126	12%	553,718	12%	555,669	11%
<b>Retained Earnings</b>	1,448,891	32%	1,506,186	33%	1,640,532	32%
<b>Other Equity</b>	(7,667)	0%	(3,323)	0%	424	0%
<b>Treasury Stock</b>	(10,480)	0%	(10,480)	0%	0	0%
<b>Non-Controlling Interest</b>	4,575	0%	3,827	0%	4,463	0%
<b>Total Equities</b>	2,458,926	54%	2,521,409	55%	2,670,349	52%

Unit: NT\$ thousand



# Future Outlook ( Operational Plan of Main BUs )

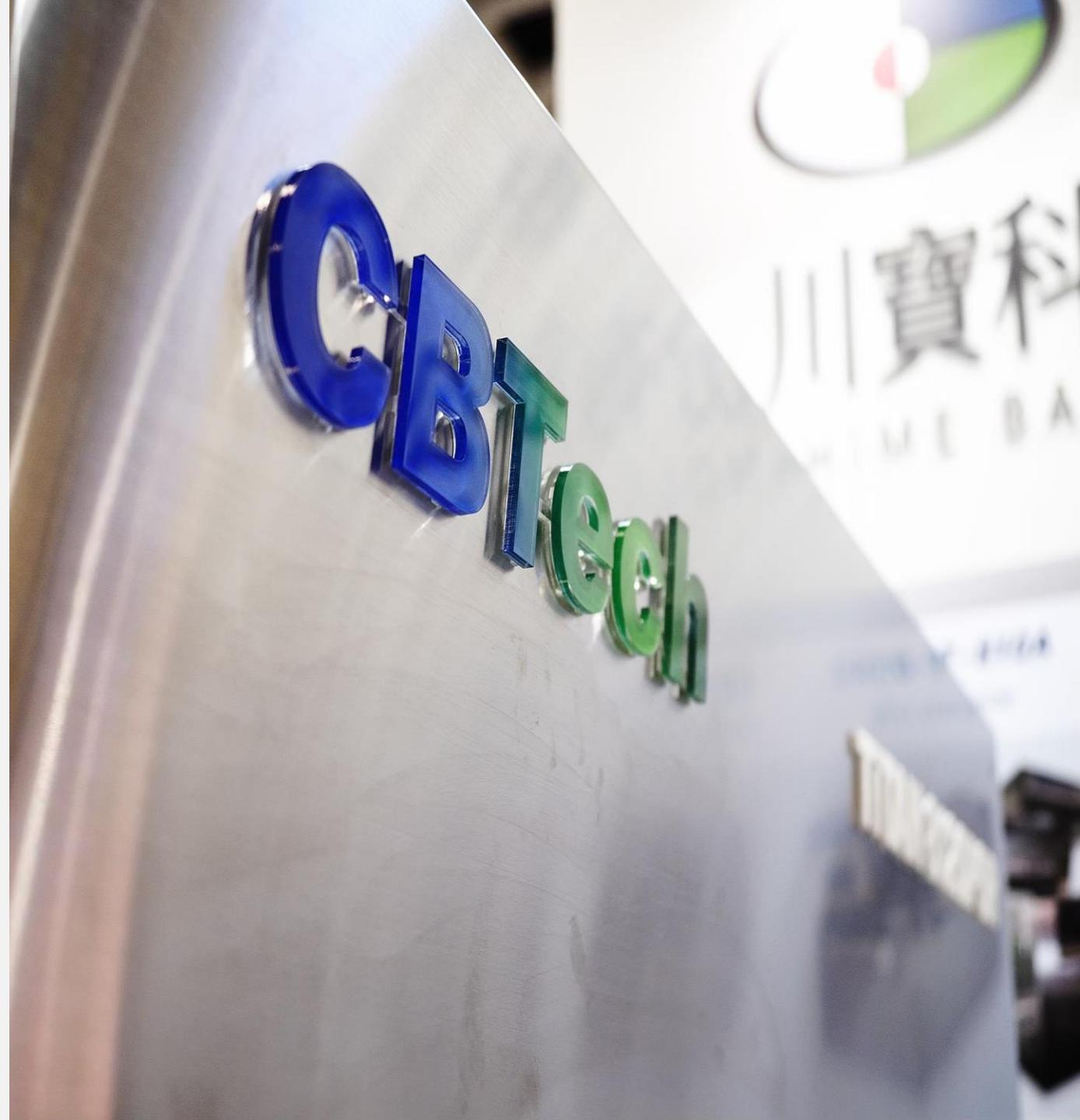


# PCB BU Future Outlook

# Current Situation

In 2021, the estimated GDP of Taiwan's circuit board industry is NT\$817.8 billion, with a growth rate of 17.5%, which is the year with the most dramatic growth since 2010.

Driven by 5G, semiconductors, electric vehicles and other innovative technologies, Taiwan's circuit board industry is expected to climb to a new peak. However, the year 2022 has not performed as expected due to geopolitical conflicts, inflations, COVID-19, intense competition with China, the rise of the trend of net zero emissions, and other factors. We hold a conservative view for the development of the equipment industry in the coming year.



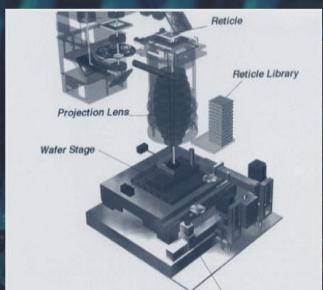
# Carry Out 3 Pillars of Sustainable Business



Contacted Exposure Unit  
FPCB RTR Exposure Unit  
Solar Cell Projector



PCB/Substrate Direct  
Imaging System  
Pattern LDI  $5\mu\text{m} \sim 40\mu\text{m}$   
Solder Mask DI



Substrate/ 2.5D 3D IC  
Stepper

Exposure Unit  
provides application  
solutions for 5G,  
electric vehicles,  
high-speed  
computing(HPC), AI,  
servers, solar cell  
projector

# Operational Plan for Next 5 Years

## Current Application (2023 ~ 2025)

- Traditional Exposure Unit/FPCB RTR Exposure Unit
- Pattern LDI / Solder Mask Direct Imaging System
- Solar Cell Projector

## Application Improvement (2023 ~ 2025)

- 5µm LDI Development Layout for Bismaleimide Triazine (BT) Board Market
- 3µm Stepper Development Layout for Ajinomoto Buildup Film (ABF) Board and 2.5D/3D IC Package Market

## Advanced Transformation ( 2025 ~ 2027 )

- BT & ABF Subtract LDI & Stepper Exposure Unit
- 2.5D/3D IC Package RDL Exposure Unit

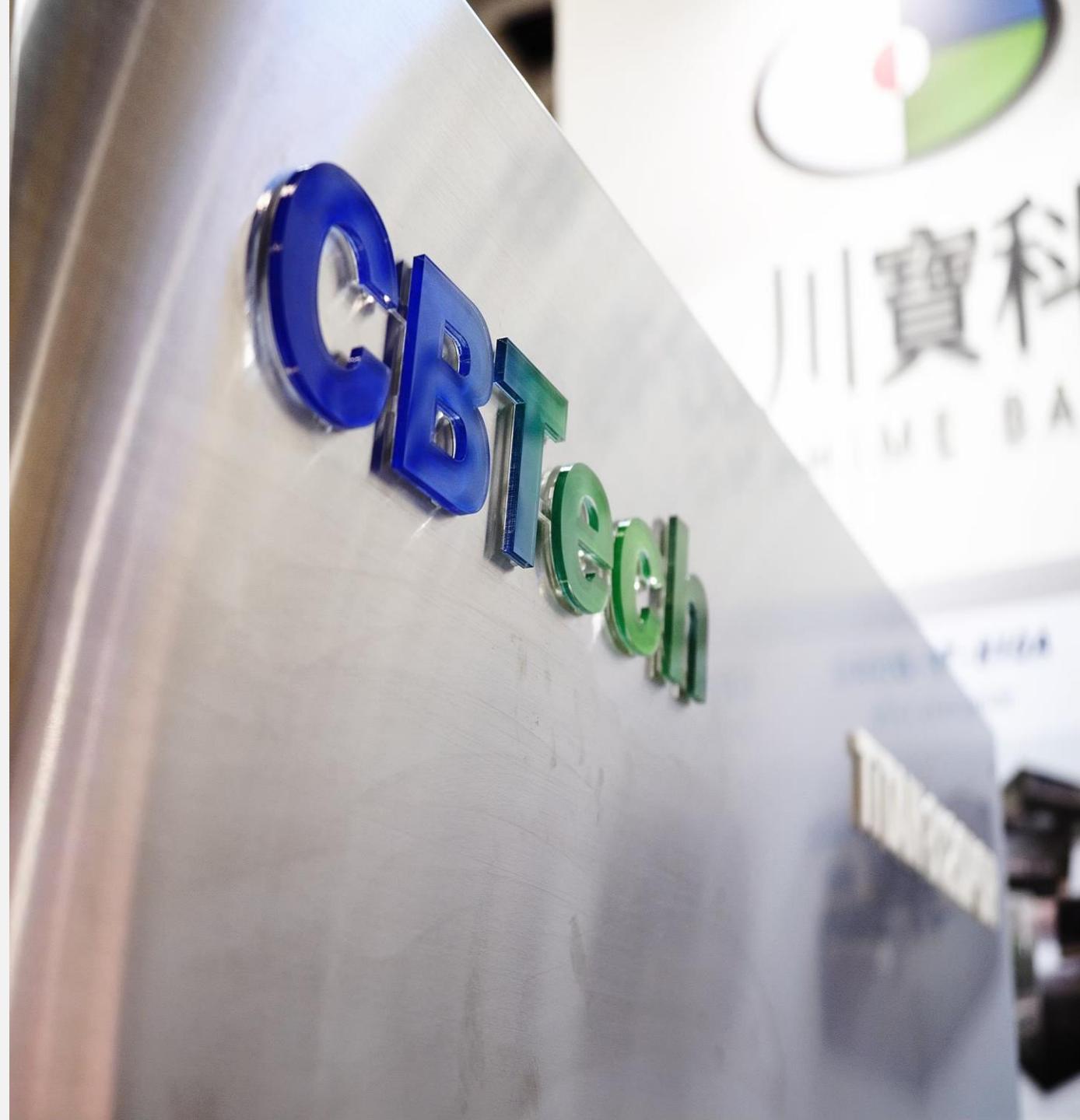


# SEMI BU Future Outlook

# Current Situation

In the past two years, the demand for process equipment is high, but the delivery time of new equipment has been extended due to supply management in the post-epidemic era and other various factors. Semiconductor manufacturers have been forced to take countermeasures. One of the main solutions is to obtain recycled semiconductor equipment. It directly leads to soaring prices, and in result, the market for mature process equipment performs outstanding.

Looking forward to 2023, despite the semiconductor industry is still facing challenges such as geopolitical, chip restrict and ban, supply management and talent gap, obtaining second-hand equipment will still be the main countermeasure regardless of its cost or delivery time. Therefore, it is expected that the revenue of BHT revenue in mature process equipment still has room for growth.



# Carry Out 3 Pillars of Sustainable Business



Semi-Equipment Refurbishing &  
Manufacturing Center



Advanced Fab Tool Automation  
RD & Manufacturing Center



Spares Agent & Brittle  
Materials Manufacturing Center

Providing  
localized  
semiconductor  
equipment and  
key components  
as solutions



# Roadmap of Organization Enterprise

# Group Competitive Strategies

## Competitive Strategies 『1 Core with 2 R&D Centers』



The Sustainable Development Committee focuses on the company's transformation from "Manufacturing" to "Technology."

Our Committee focuses on the technology cultivation and the long-term development, and adheres to the principles of "Corporate Governance and Integrity Operations," "Green Products and Environmental Protection" and "To Take Care of Employees and Caring for Minority," which allow us to be the model for enterprises domestically and to pursue sustainable business development.



Hsinchu R&D Center focuses on advance fab tool automation, software & mechanism development.



Luzhu Materials R&D Center focuses on optical design, optical coating, sputtering AST and critical material development.

# Group Sustainable Development Goals (SDGs)

## SDGs holds 3R 『REUSE, REDUCE & RECYCLE』

In response to the Global Net-Zero Emissions trend, Environment-Friendly, and providing customers Sustainable Development Solutions with our sustainable innovation



REUSE

Provides customers localized refurbishing equipment and spare parts and solution for regeneration resources



REDUCE

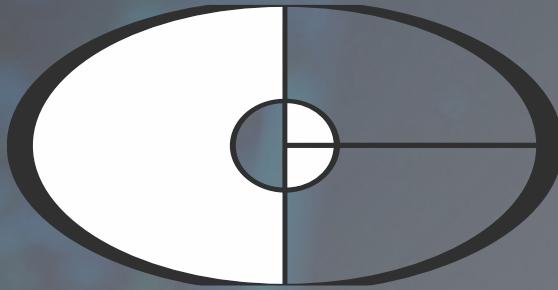
Continue to invests in green energy and optimization facility /equipment, and to implement Energy Management System (EMS)



RECYCLE

Actively invests in regenerating resources and circular economy technology development

Assists customers in driving Net Zero Emissions



# 川寶集團

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